





FIG.1:Power dissipation vs. on-state current
(per thyristor or diode)
 $P_T(AV)/P_F(AV)(W)$

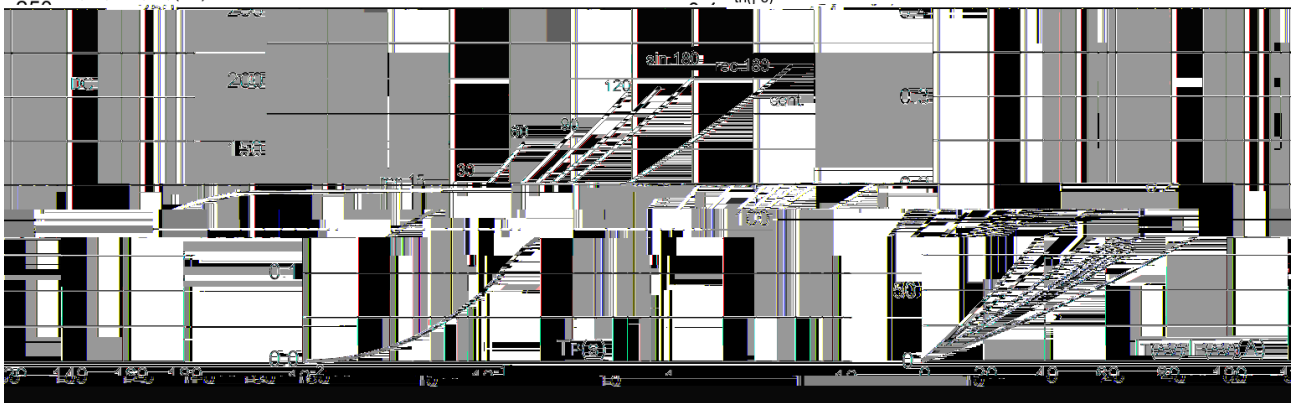


FIG.2: Maximum transient thermal impedance
junction to case(per thyristor or diode)
 $R_{th(j-c)}(^{\circ}C/W)$

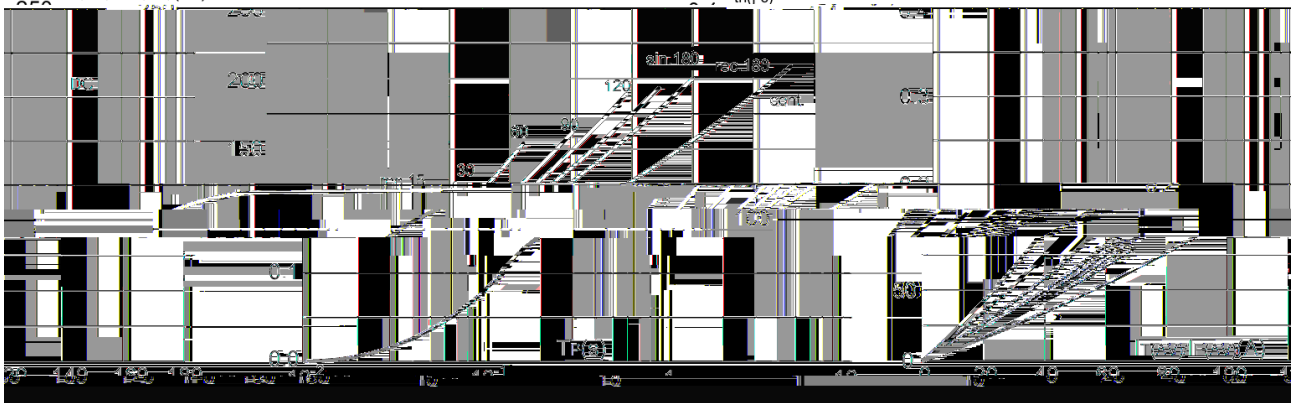


FIG.3:Forward characteristics
(per thyristor or diode)
 $I_F(A)/I_T(A)$

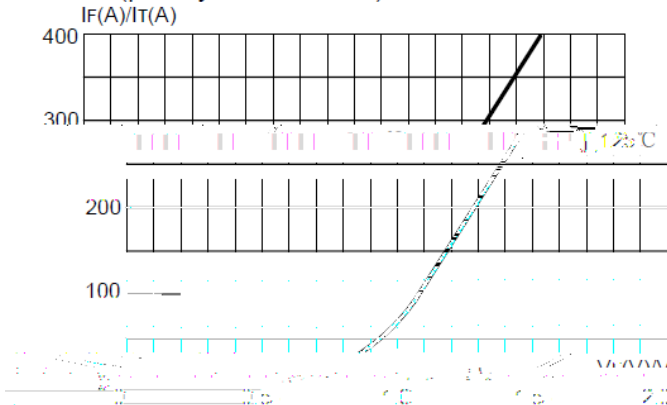


FIG.4: Relative variations of gate trigger current, holding current and latching current versus junction temperature
 $I_{GT, IH, IL}(T_J)/I_{GT, IH, IL}(T_J=25^{\circ}C)$

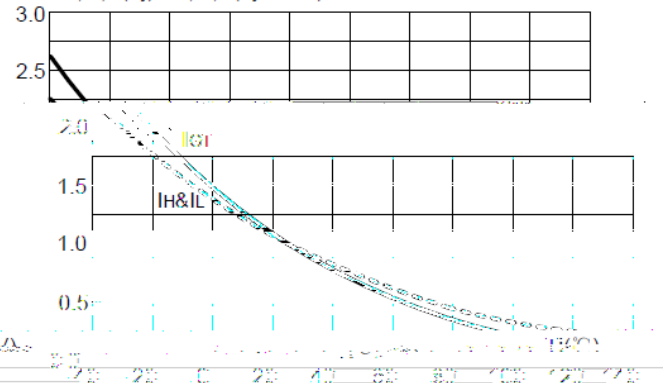


FIG.5 Gate trigger characteristics

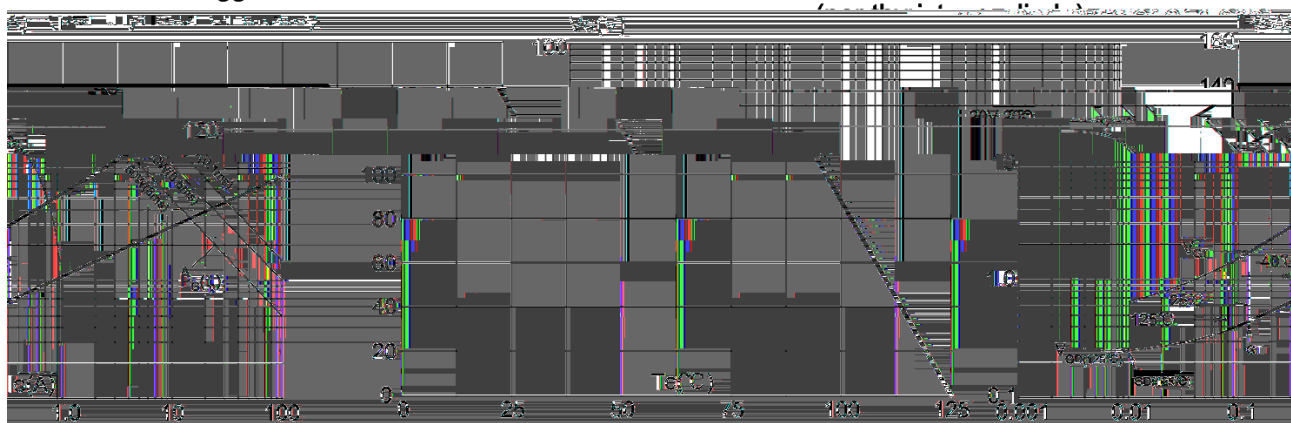


FIG.6: Forward current vs. case temperature

